

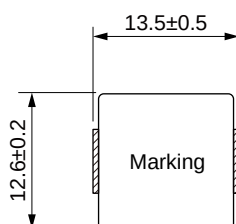
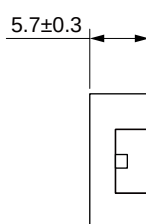
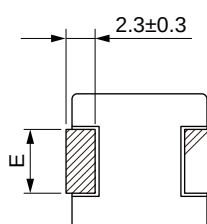
MDSA Series

SMD Low Profile High Current Molded Inductor

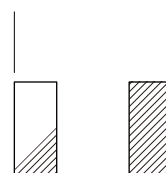
Size 1360



Dimensions: [mm]



Land Pattern: [mm]



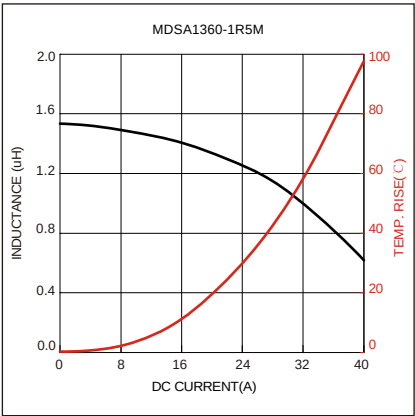
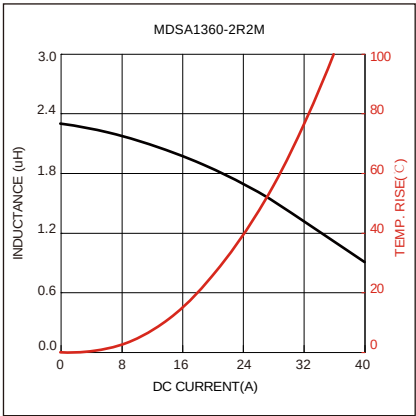
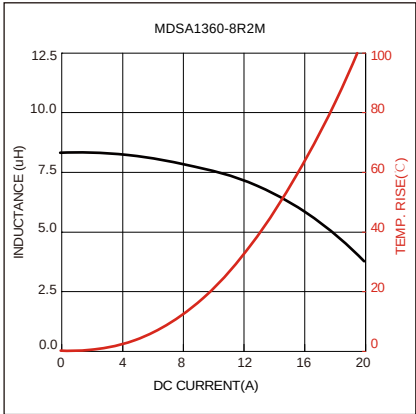
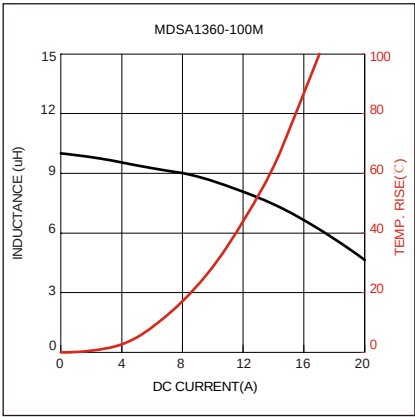
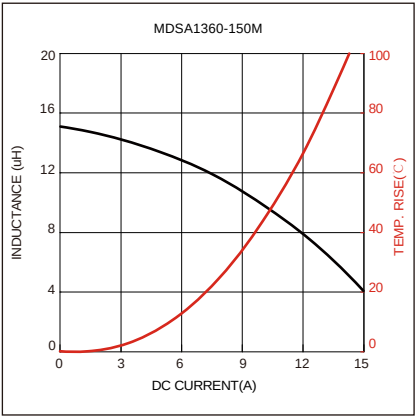
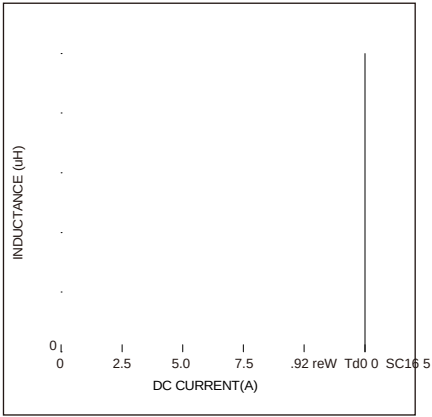
Electrical Properties:

						Inductance Typ. (mH)	DC Resistance Typ. (mΩ)	DC Resistance Max. (mΩ)	Q (min)
					30.0	28.0	2.42		4.0±0.3
				12.0	28.0	28.0		6.80	4.7±0.3
				11.0	17.0	14.0	13.7	16.2	4.7±0.3
			10.0	8.00	10.0	8.70	24.3	29.3	4.7±0.3
		5%			2.50			68.7	4.7±0.3

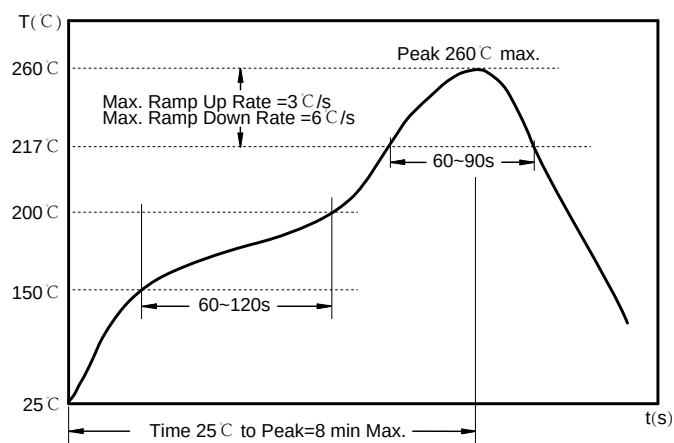
...to drop approximately 50%
The actual value of DC current when the temperature rise is 50°C±40°C



Typical Electrical Characteristics:



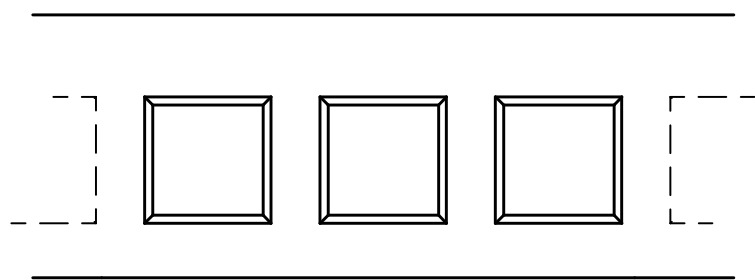
Soldering Reflow:



Preheat condition: 150 ~200℃ / 60~120 sec.
Allowed time above 217℃ : 60~90 sec.
Max temperature: 260℃ .
Max time at max temperature: 10 sec.
Allowed Reflow time: 2x max.

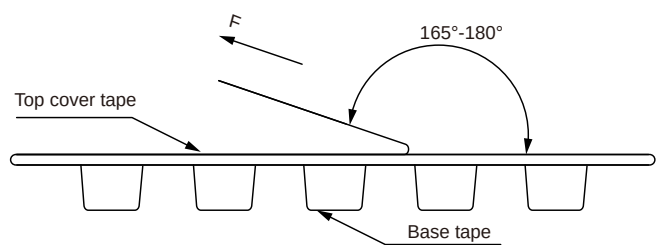
Packaging Information:

Tape Dimension :



A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
13.1±0.1	14.0±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	6.3±0.1	1.75±0.1	0.50±0.05

Peel force of top cover tape:

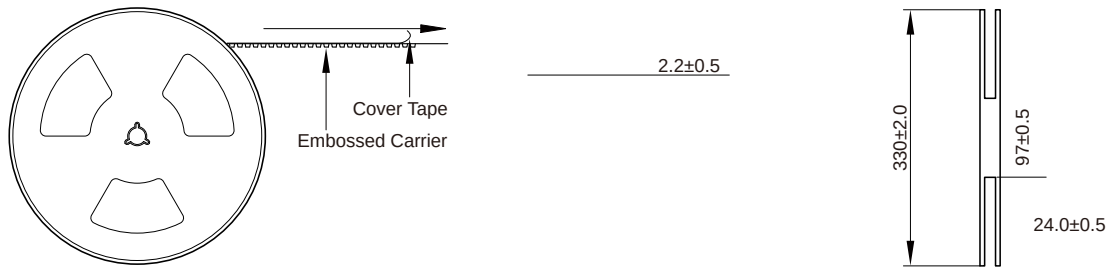


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	KH+Printing Inductance+period)
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Reel Dimension: [mm]



Packaging Quantity: